# Fair-Rite P/N 2506031217H0

## H Chip Bead Material Grade    Nominal Chemical Composition

Wt of core (g)=

| Ferrite -Compound | CAS Number | wt % | 0.0048 |
|---|---|---|---|
| $Fe_2O_3$ | 1309-37-1 | 60 | 0.002880 |
| NiO | 1313-99-1 | 23 | 0.001104 |
| ZnO | 1314-13-2 | 8 | 0.000384 |
| CuO | 1317-38-0 | 5 | 0.000240 |
| $Co_3O_4$ | 1308-06-1 | 3 | 0.000144 |
| MnO | 1344-43-0 | 1 | 0.000048 |

**Compound Weight (g) Breakdown of H Chip Bead Material Grade**

Wt of termination (g)=

| Termination Plating - Elements | CAS Number | wt % | 0.0012 |
|---|---|---|---|
| Sn | 7440-31-5 | 14.3 | 0.0001716 |
| Ni | 7440-02-0 | 6.9 | 0.0000828 |
| Ag | 7440-22-4 | 78.8 | 0.0009456 |

**Element Weight (g) Breakdown of Pb- Free Termination Plating**

**Supporting notes:**

1. P/N 2506031217H0 consists of:
   a core H Chip Bead Material Grade
   b Termination Plating SnNiAg
2. Moisture Sensitivity Level (MSL)= 1
3. Max Reflow Temp= 260 degC
4. Max Time at Max Reflow Temp= 40 sec
5. RoHS 6/6 Compliant Terminations/ Wire are backwards compatible with standard Soldering Processes
6. RoHS Conversion Date= 1/1/2005
7. RoHS Compliance Marking is Contained on Shipping Labels

## Calculated Maximum Levels of RoHS Restricted Substances Present in H Chip Bead Material Grade

Wt of core (g)=

| Impurity Substance | RoHS Threshold (ppm): | ppm | 0.0048 |
|---|---|---|---|
| Cr+6 | 1000 | 0.00 | 0 |
| Cd | 100 | 0.00 | 0 |
| Hg | 1000 | 0.00 | 0 |
| Pb | 1000 | 0.00 | 0 |
| PBB | 1000 | 0.00 | 0 |
| PBDE | 1000 | 0.00 | 0 |
| Bis(2-Ethylhexyl) phthalate (I | 1000 | 0.00 | 0 |
| Benzyl butyl phthalate (BBP) | 1000 | 0.00 | 0 |
| Dibutyl phthalate (DBP) | 1000 | 0.00 | 0 |
| Diisobutyl phthalate (DIBP) | 1000 | 0.00 | 0 |

**RoHS Impurity Substance Weight (g) Breakdown of H Chip Bead Material Grade**